# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model:** HP Pro c640 Chromebook Enterprise

[List multiple models if applicable.] HP Pro c640 Chromebook / Bruno / OGC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

**NOTE:** Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td></td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [x] screws [ ] snaps [ ] adhesive [ ] other. Explain ______</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps 14”</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC Cable for External Power Supply</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs)</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**EL-MF877-00**

**Template Revision C**

Last revalidation date 09-May-2018

HPI instructions for this template are available at [EL-MF877-01](#)
### Item Description

<table>
<thead>
<tr>
<th>Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
<tr>
<td>including liquids, semi-liquids (gel/paste) and toner</td>
<td>chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw Driver</td>
<td>PH00 / PH0 / PH1</td>
</tr>
<tr>
<td></td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Dis-fasten BASE Screw*7
2. Remove BASE and remove Battery connector
3. Dis-fasten Battery and speaker screw*7
4. Remove Battery and Speaker
5. Dis-fasten FAN screw*3, Remove FAN
6. Dis-fasten DB Screw*3, remove connector and remove DB
7. Dis-fasten CPU BKT screw*4
8. (10→8) Remove Thermal module
9. (8→9) Remove MB connector (LVDS, KB, BL, TP, Antenna, camera, FPR)
10. (9→10) Dis-fasten MB screw*4
11. Remove MB
12. Dis-fasten KB hook screw*1 and remove KB hook*1
13. Dis-fasten TP screw*7
14. Remove TP pad, TP-FFC and BKT
15. Dis-fasten FPR BKT screw*1 and remove FPR BKT*1, FPR module*1
16. TOP remove release, dis-fasten Hinge screw*4
17. Remove TOP part
18. Remove hinge cap
19. Dis-fasten hinge screw*3, Remove Bezel
20. Remove Panel Easy pull Adhesive and remove LCD cable connector and panel
21. Dis-fasten hinge bkt screw*6 and LCD panel BKT screw*2

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HPI instructions for this template are available at [EL-MF877-01](EL-MF877-01)
22. Remove hinge*2 (left and right), LCD panel BKT and LVDS cable
23. Remove camera module and camera cable connector
24. The END

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.2.1

1. Dis-fasten BASE Screw*7

2. Remove BASE and remove Battery connector

3. Dis-fasten Battery and speaker screw*7
4. Remove Battery and Speaker

5. Dis-fasten FAN screw*3. Remove FAN

6. Dis-fasten DB Screw*3. Remove connector and remove DB

HPI instructions for this template are available at EL-MF877-01
7. Dis-fasten CPU BKT screw *4

8. Remove Thermal module

9. Remove MB connector (LVDS, KB, BL, TP, Antenna, camera, FPR)

HPI instructions for this template are available at EL-MF877-01
10. Dis-fasten MB screw *4

11. Remove MB

12. Dis-fasten KB hook screw*1 and remove KB hook*1
13. Dis-fasten TP screw*7

14. Remove TP pad, TP-FFC and BKT

HPI instructions for this template are available at EL-MF877-01
15. Dis-fasten FPR BKT screw*1 and remove FPR BKT*1, FPR moudle*1

16. TOP remove release, dis-fasten Hinge screw *4

17. Remove TOP part
18. Remove hinge cap


20. Remove Panel Easy pull Adhesive and remove LCD cable connector and panel
21. Dis-fasten hinge bkt screw *6 and LCD panel BKT screw*2

22. Remove hinge*2 (left and right), LCD panel BKT and LVDS cable

23. Remove camera module and camera cable connector
24. The END